

ABSTRACT OF THE DISCLOSURE

Provided a semiconductor device including: a wiring board; a semiconductor chip having a pad electrically connected to a wiring  
5 on the wiring board; a second semiconductor chip provided on the wiring board at a position facing a side of the semiconductor chip, having passive elements integrated therein, and having pads for external connection to which both ends of the passive elements are connected respectively and at least one of which is electrically  
10 connected to the wiring on the wiring board electrically connected to the pad of the semiconductor chip.